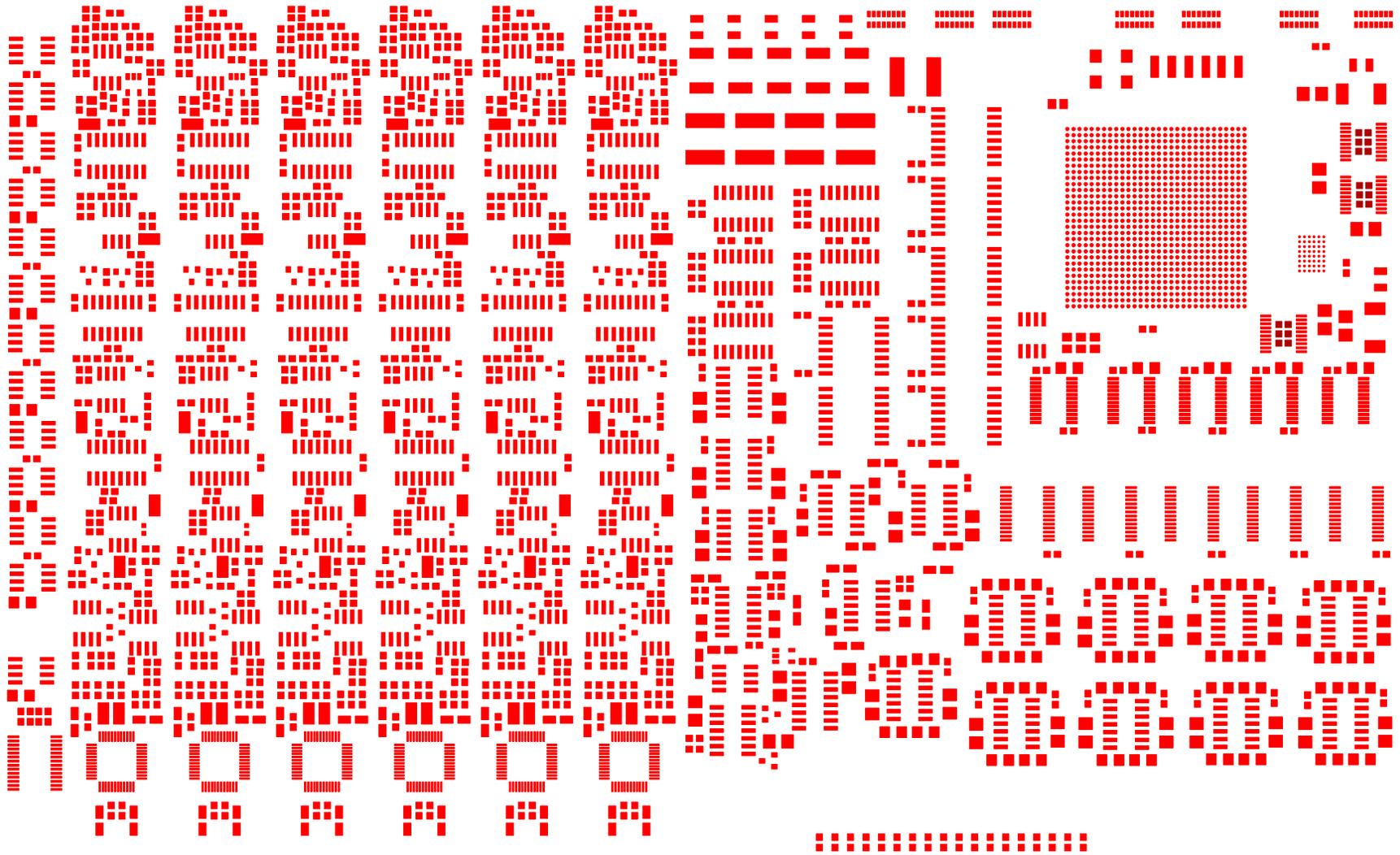
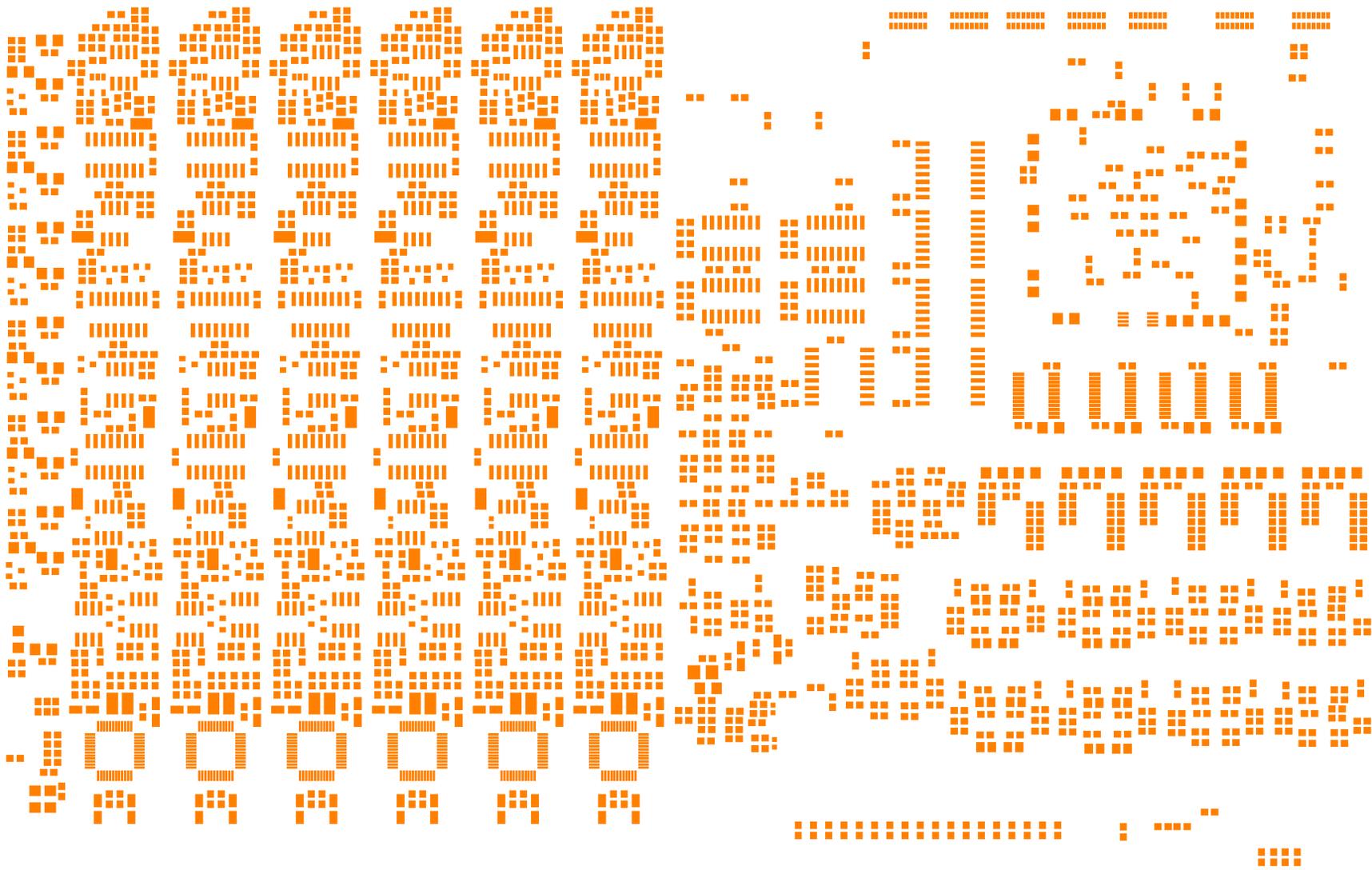
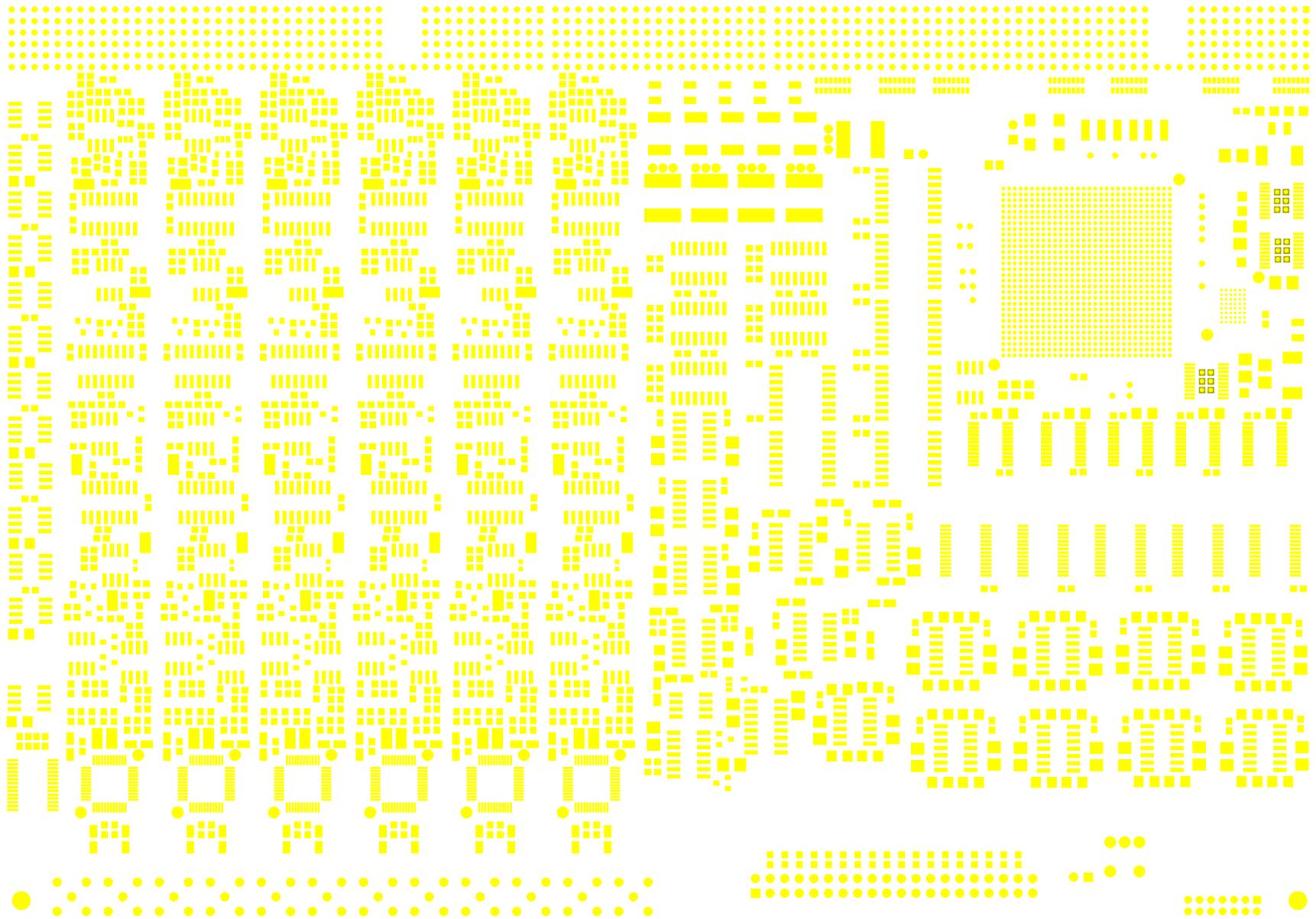


Paste Top

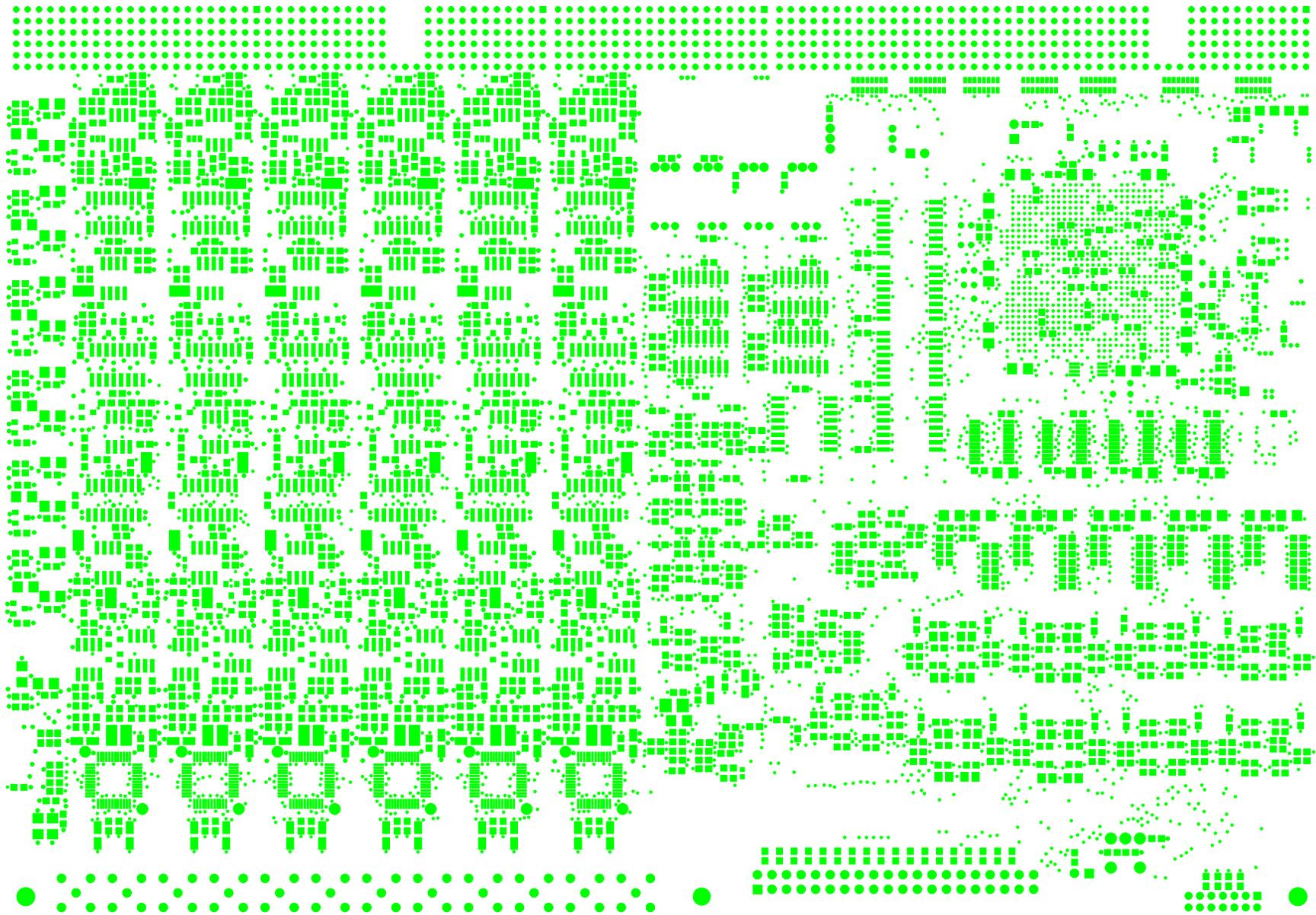




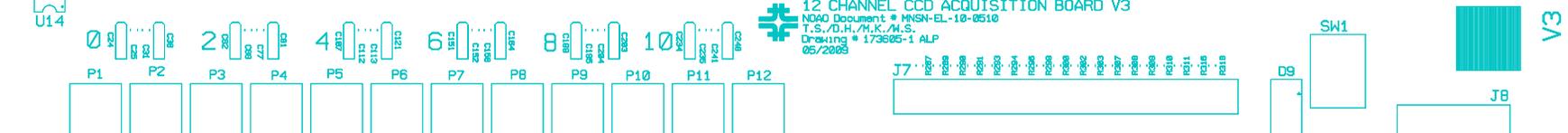
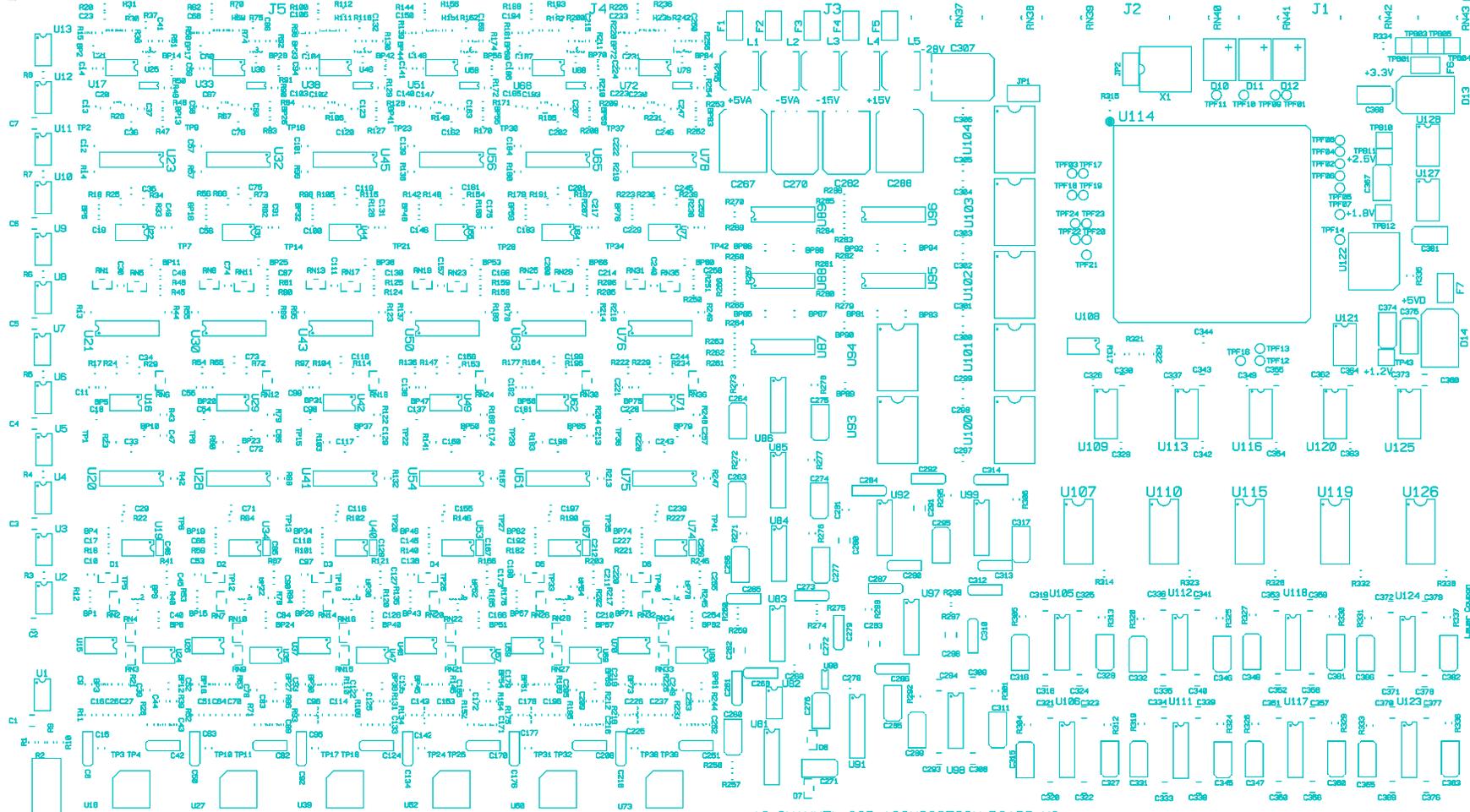
Paste Bottom



Solder Mask Bottom



F E D C B A

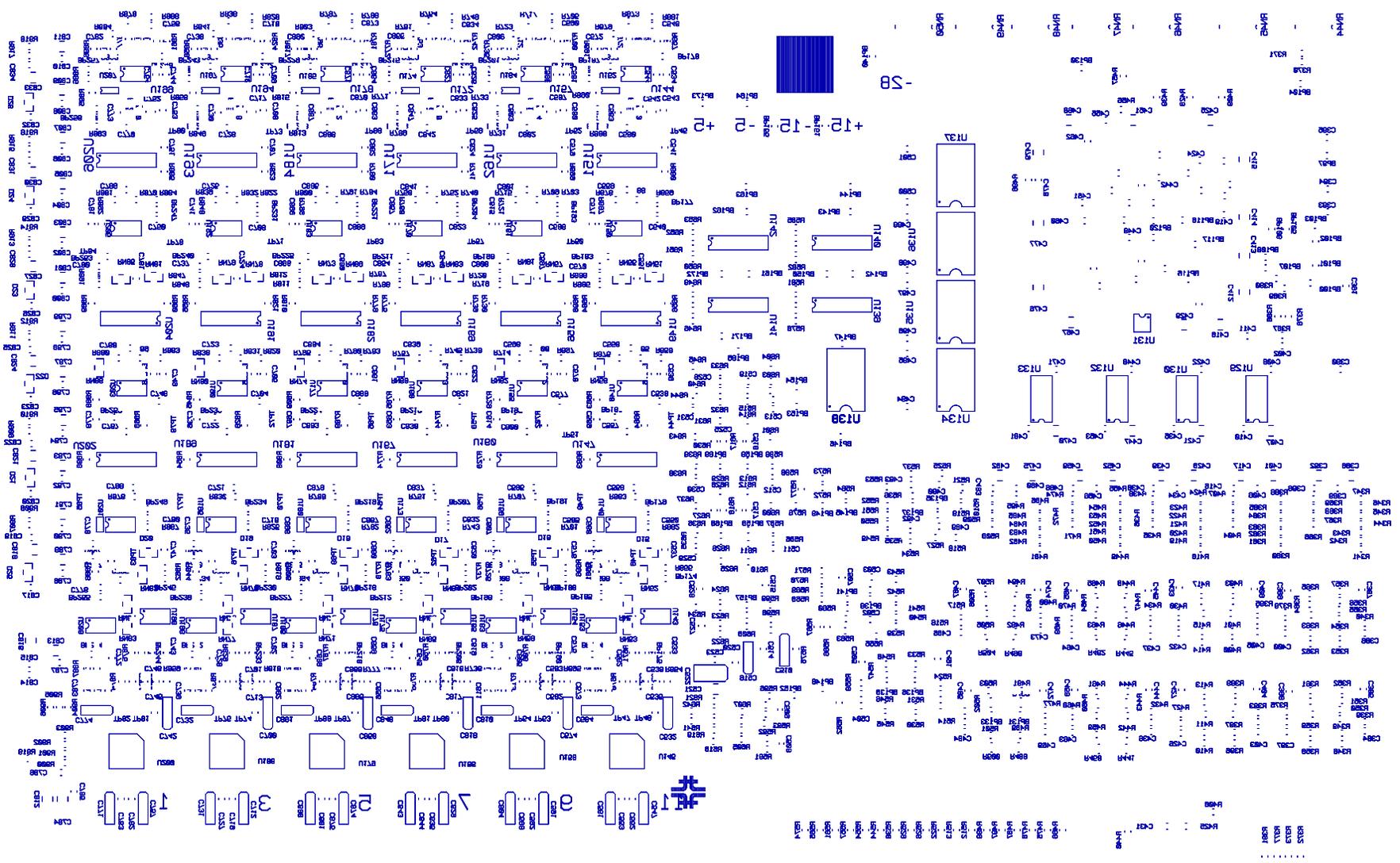



12 CHANNEL CCD ACQUISITION BOARD V3
 NDAQ Document # MNSN-EL-10-0510
 S. D. H. M. K. H. S.
 Drawing # 173605-1 ALP
 05/2009

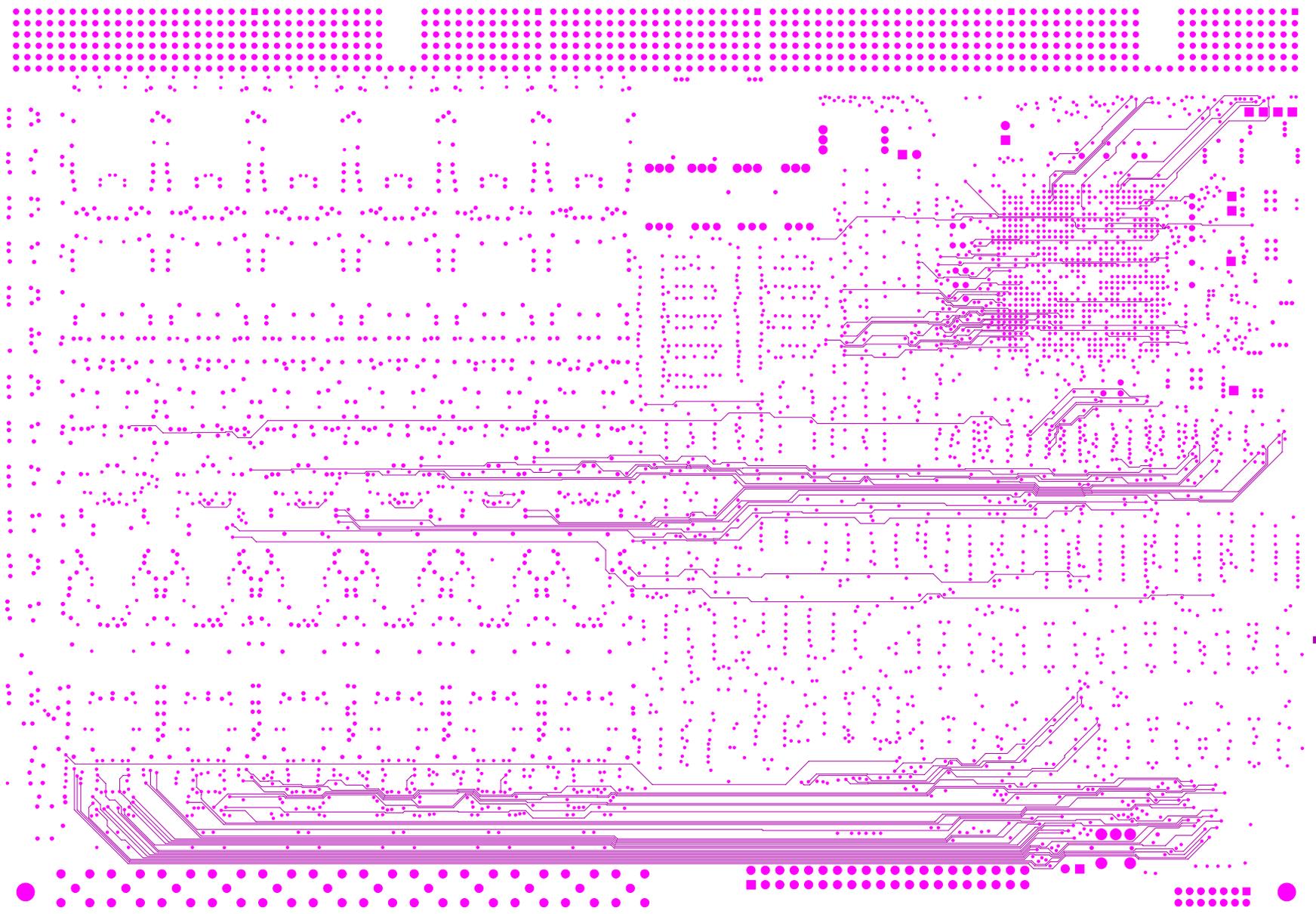
V3

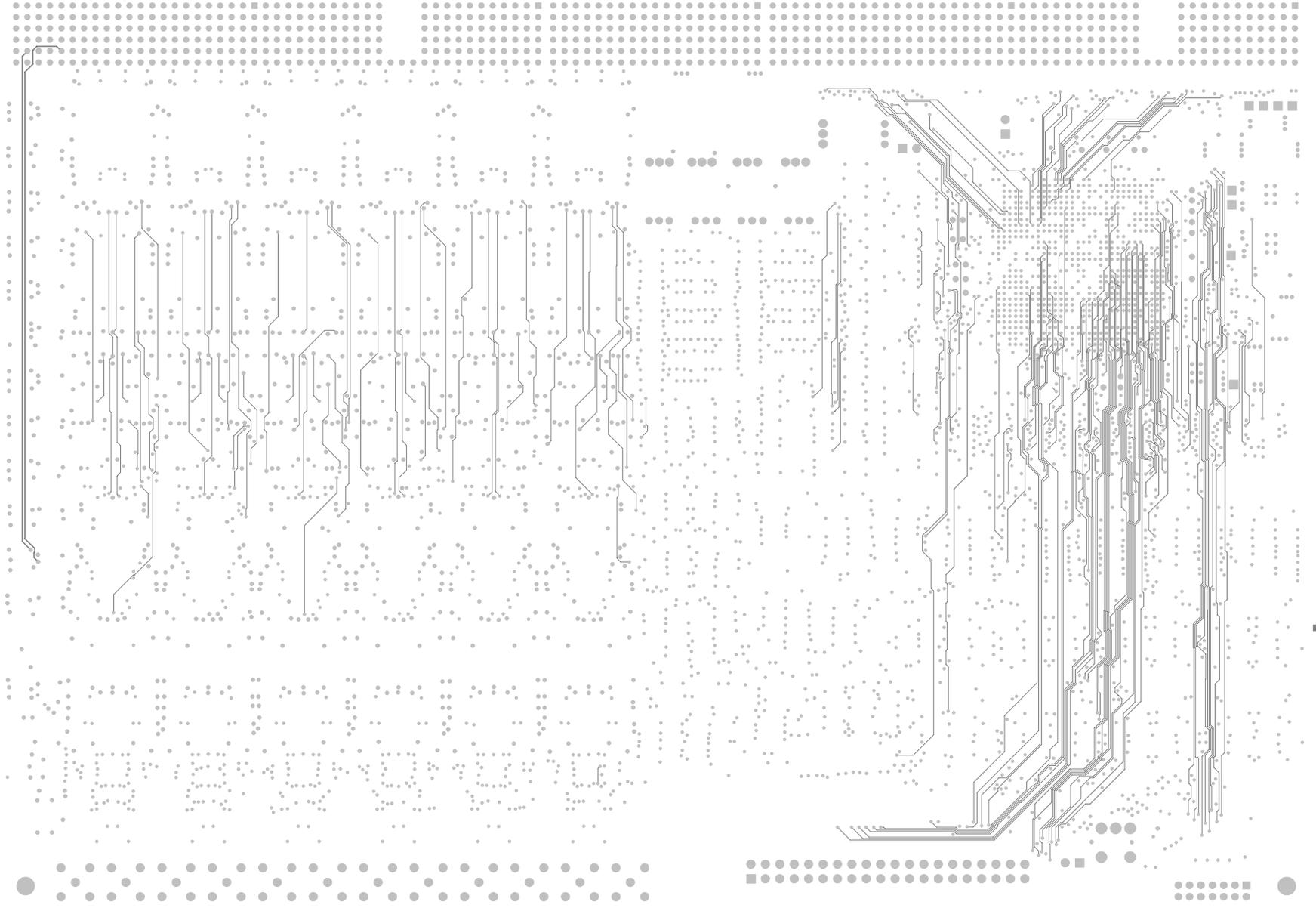
Layer: Copper

511k Top

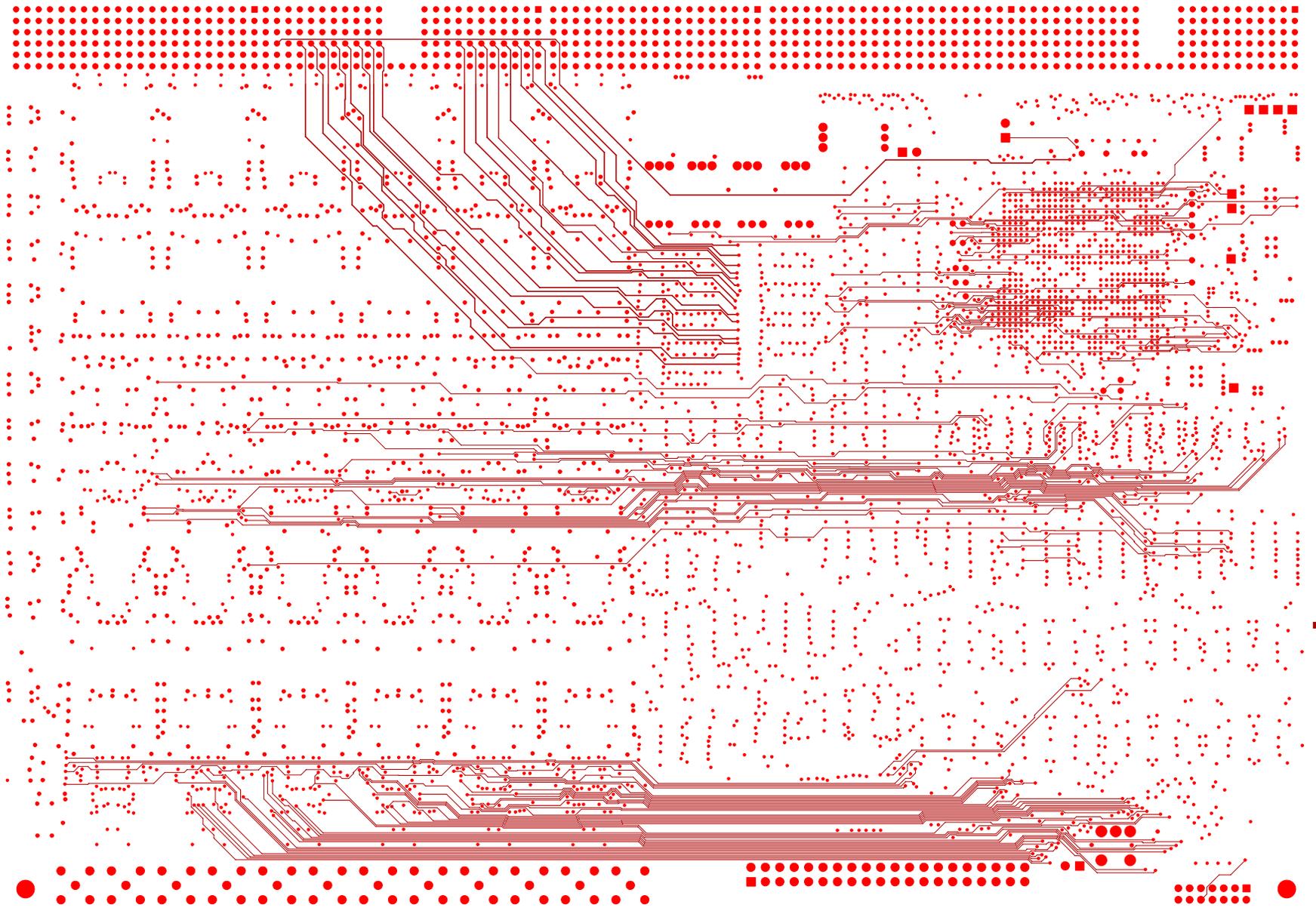


EtchLayer9.gds



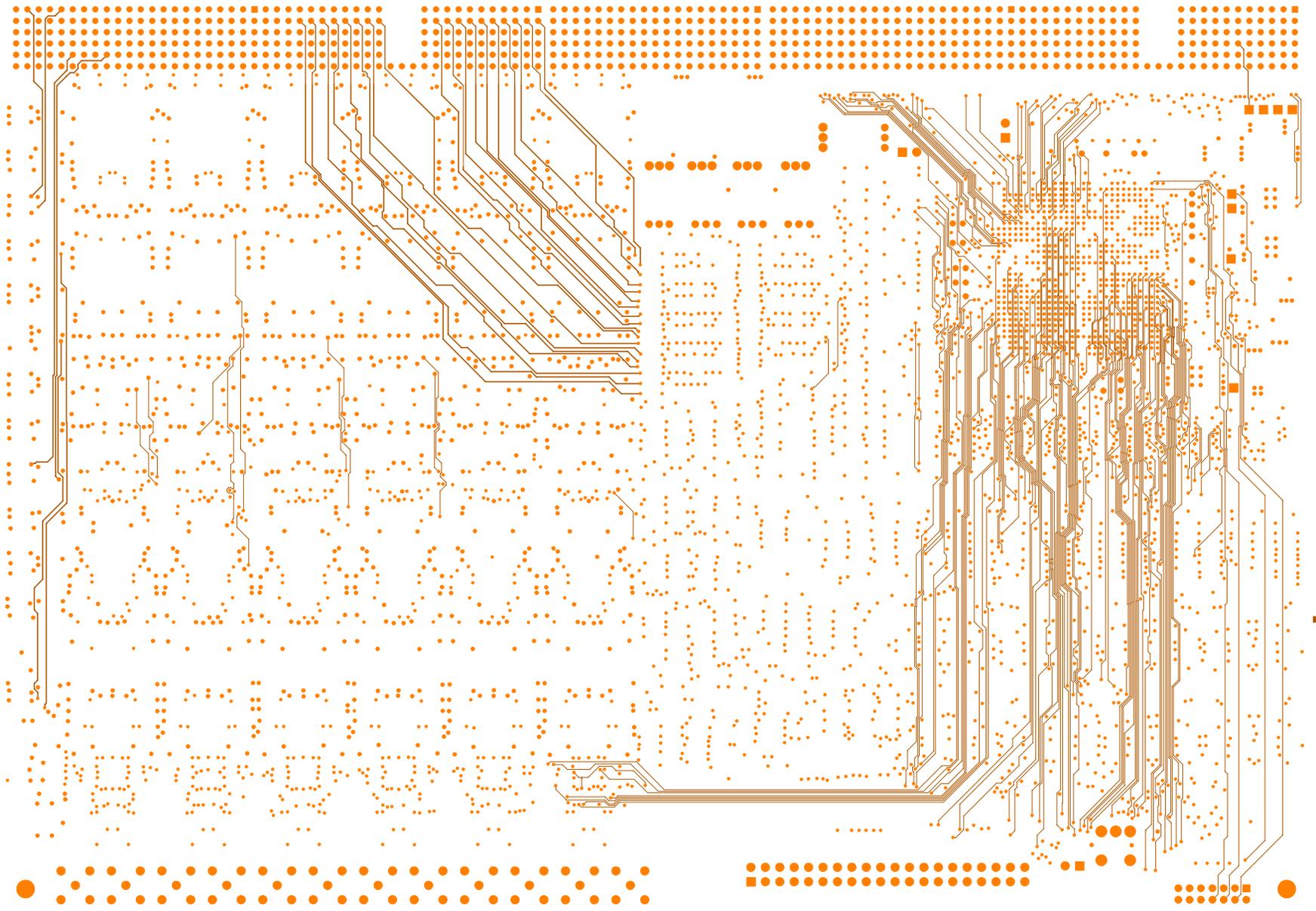


EtchLayer8.gbr

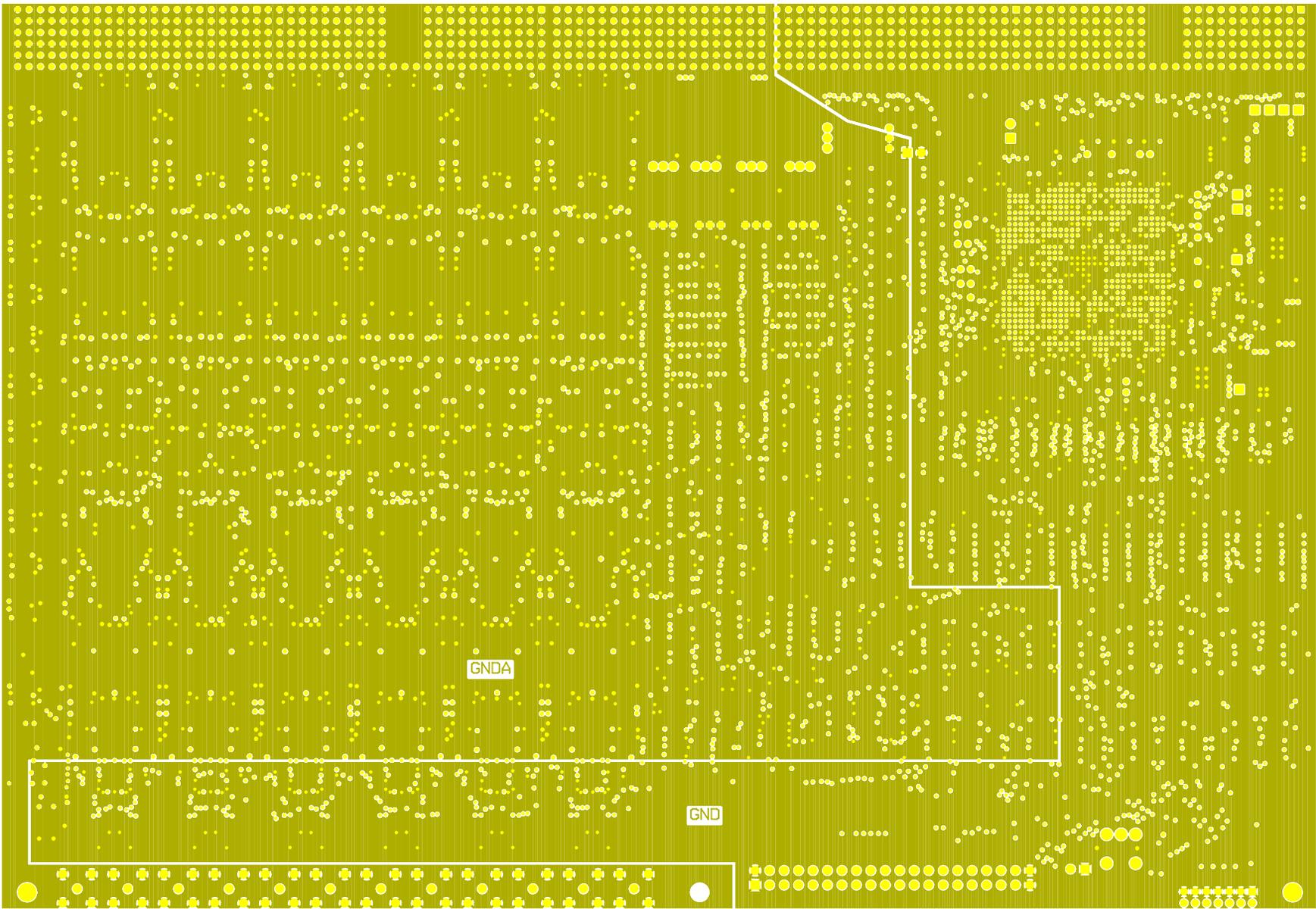


Etc\layer7.gdp

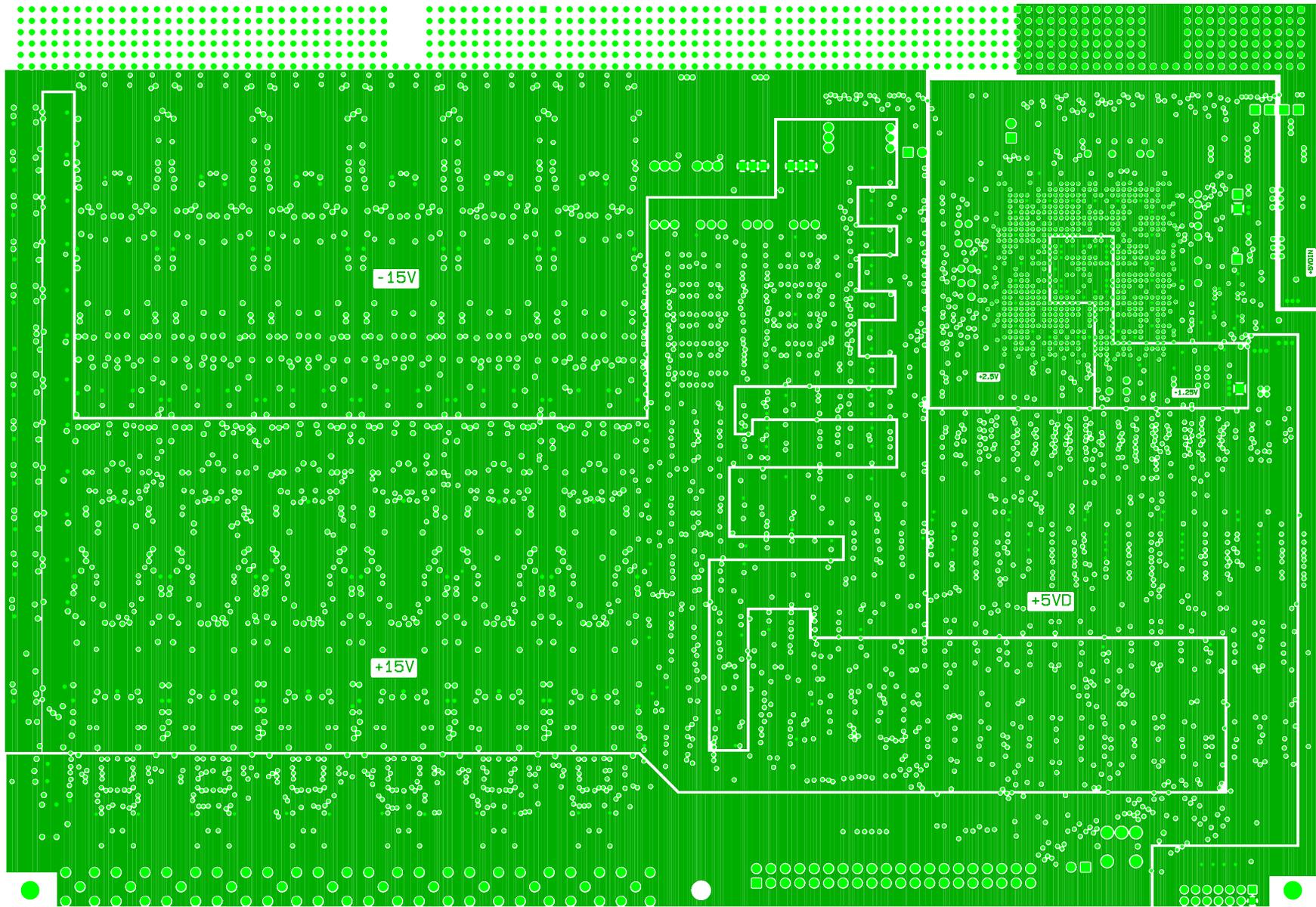
EtcLayer6.gbr



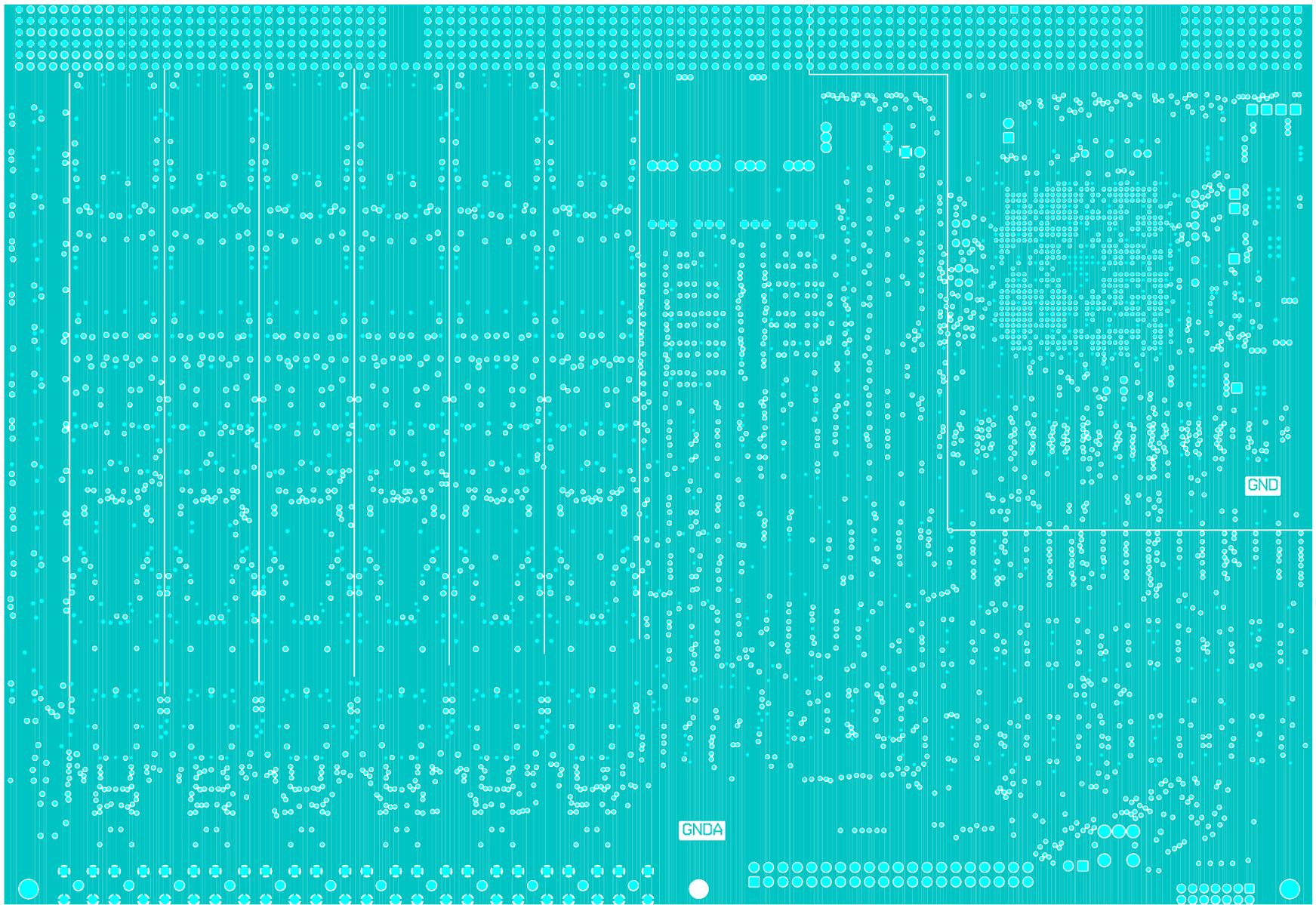
EtchLayer5.gao



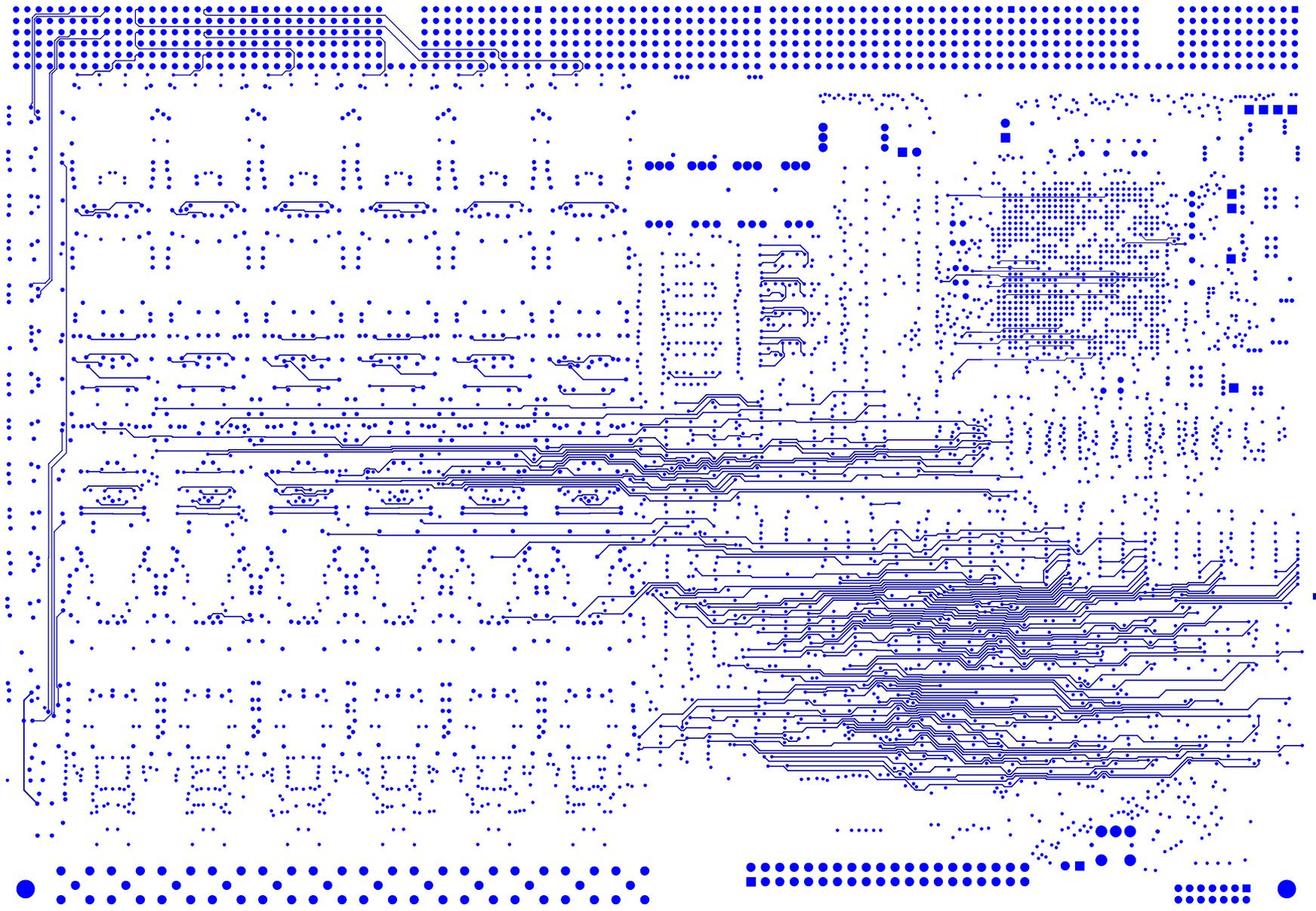
EtoLayer4.gbr



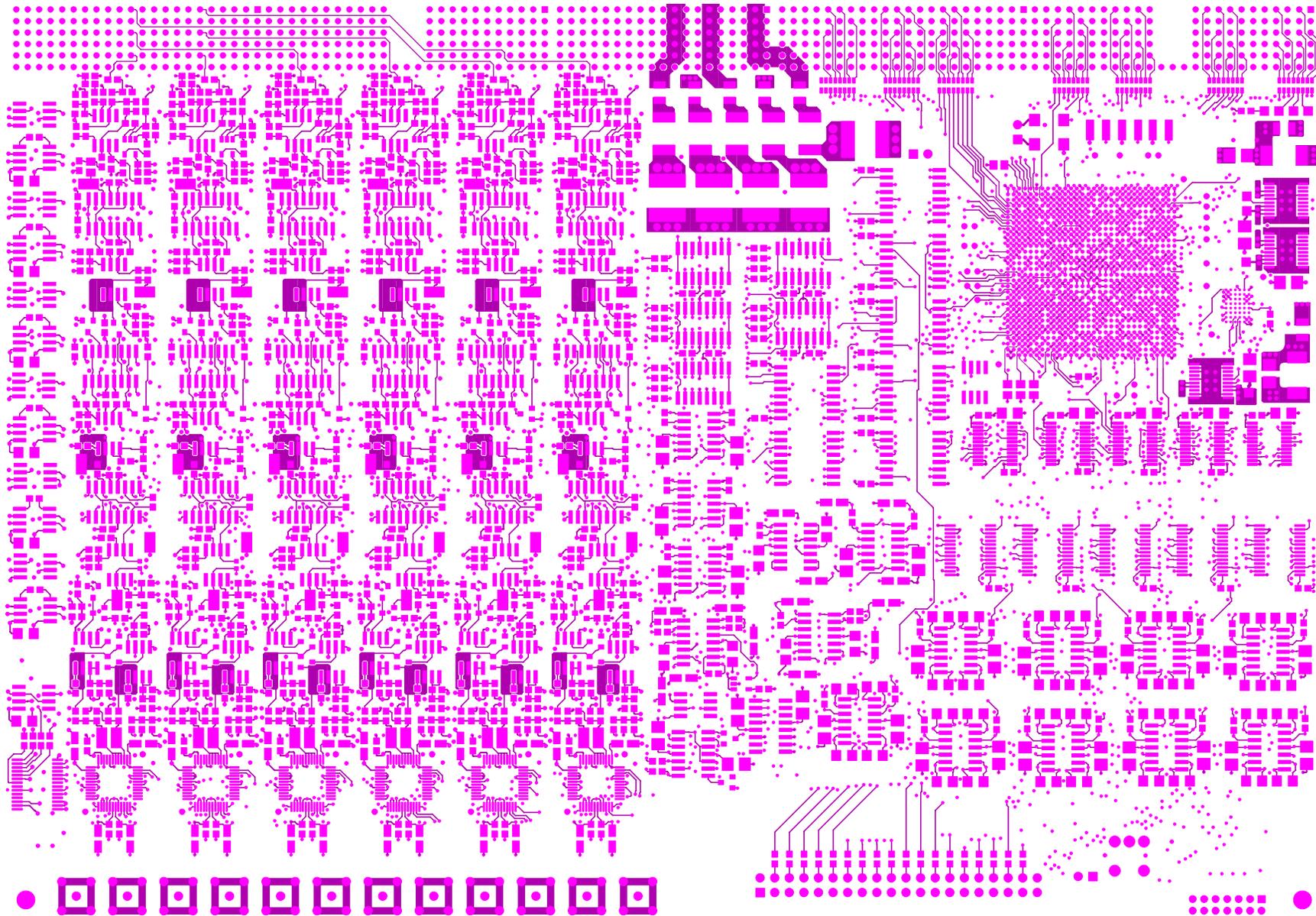
Etohlayer3.gds

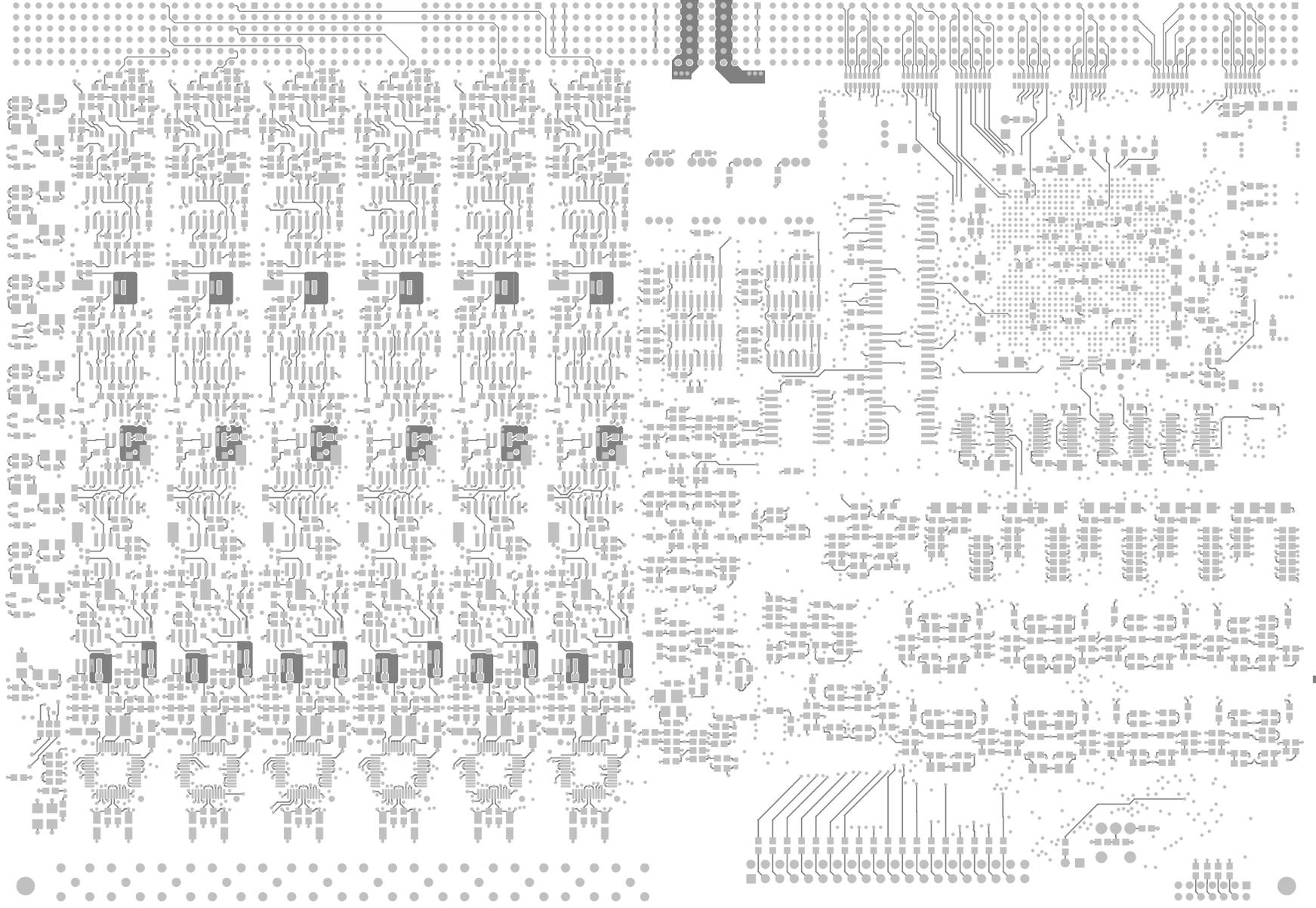


EtoHLayer2.gbr



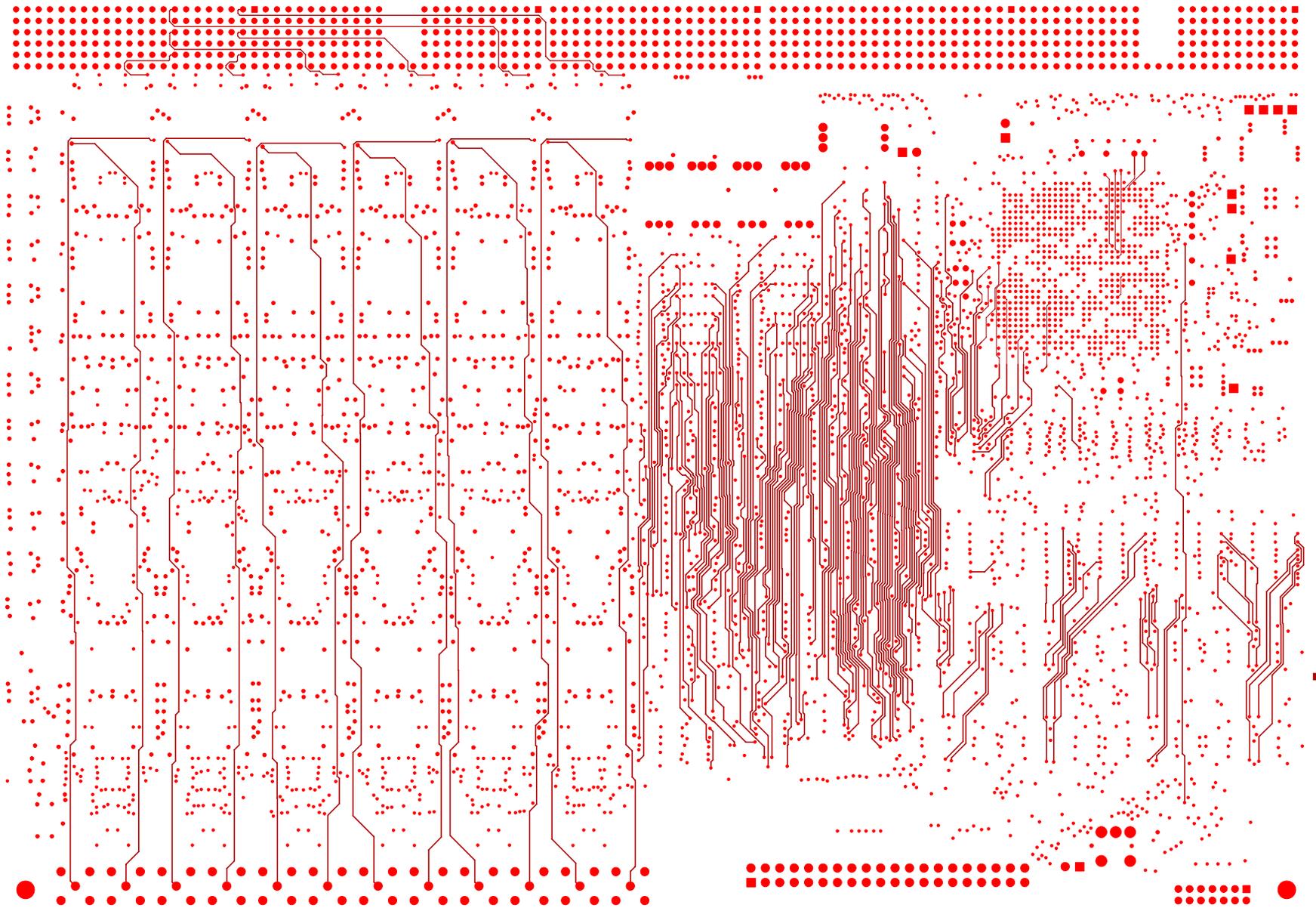
EtchLayer1Top.gbr



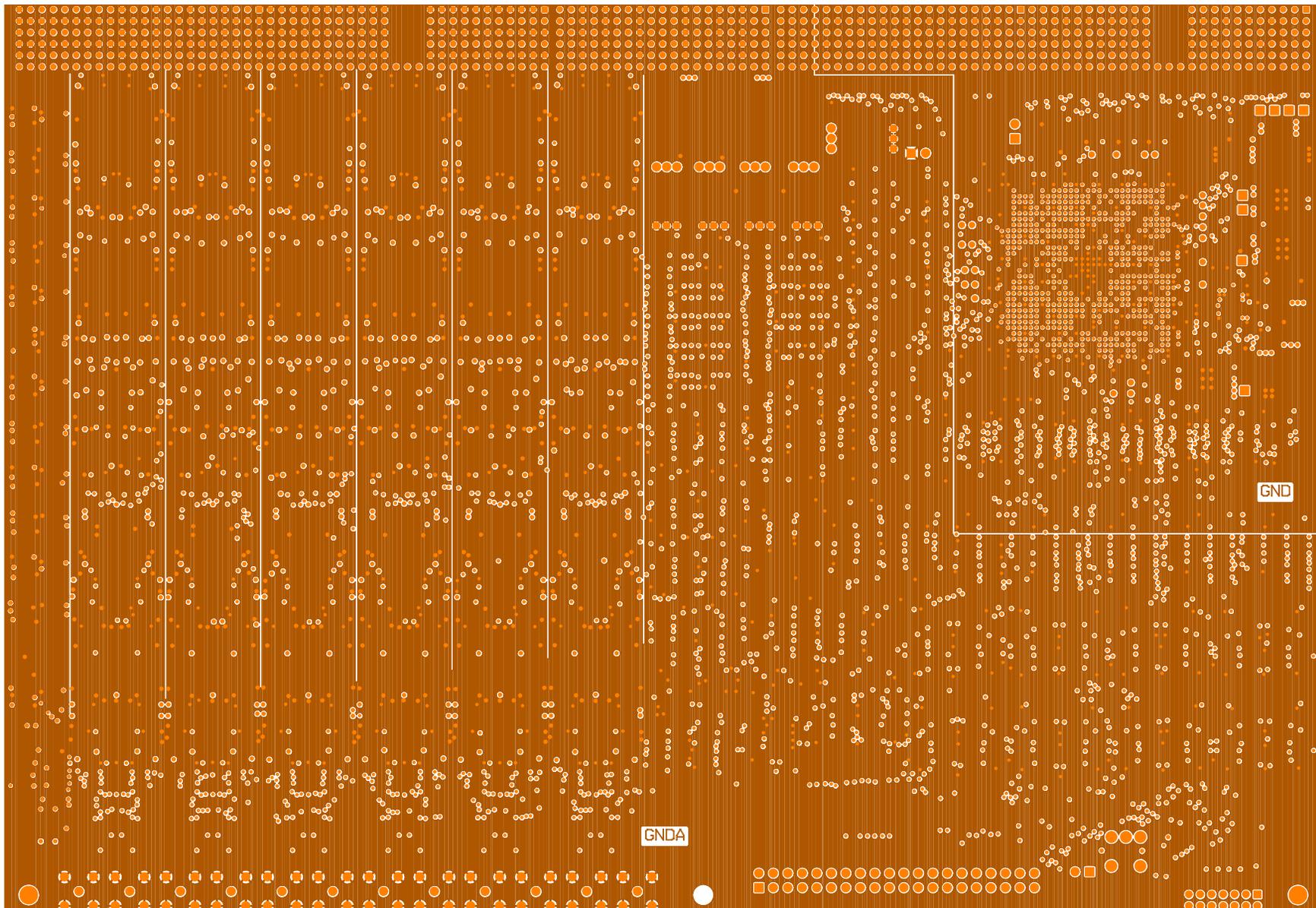


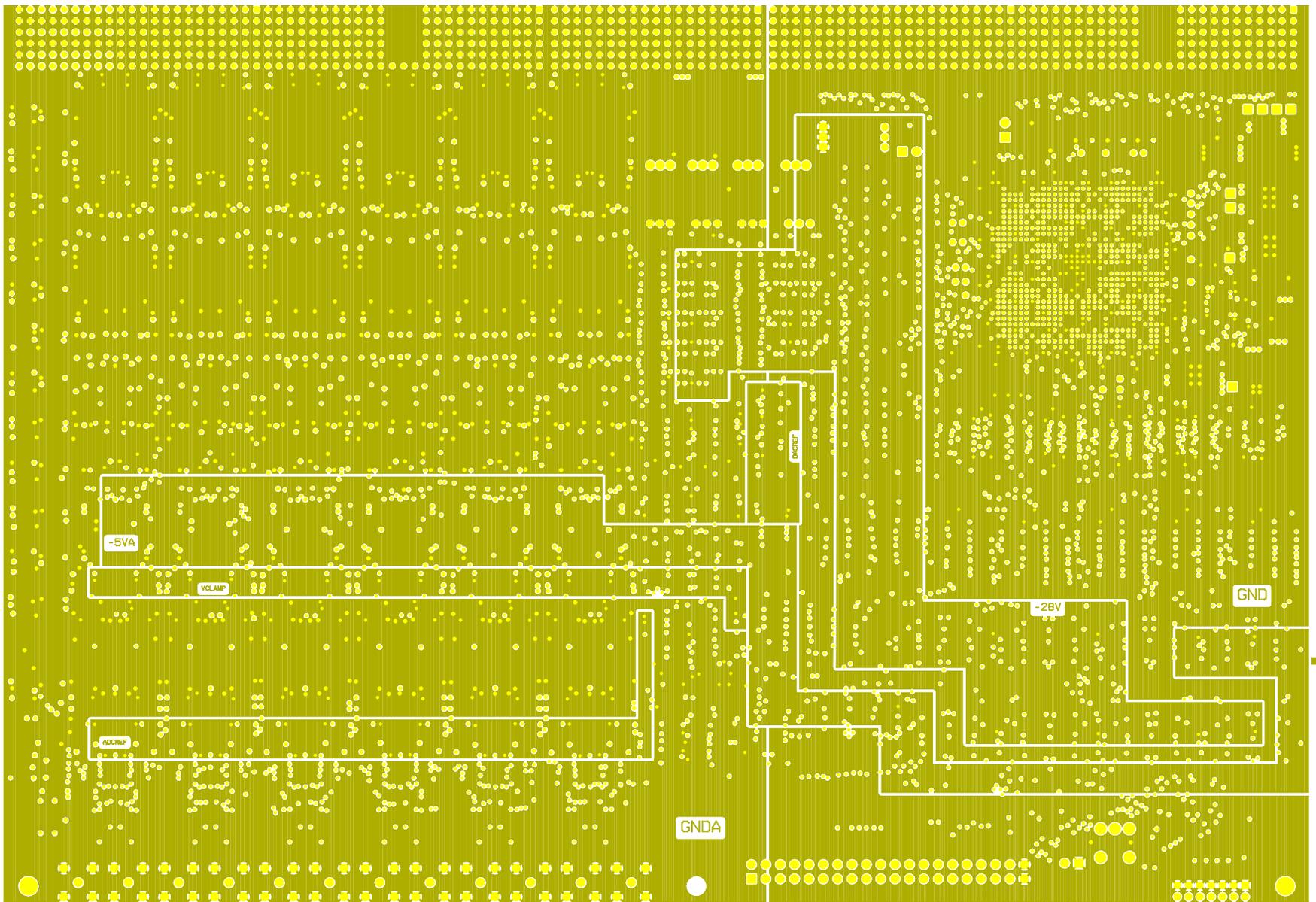
Etohlayer16Bottom.gbr

EtchLayer15.gbr



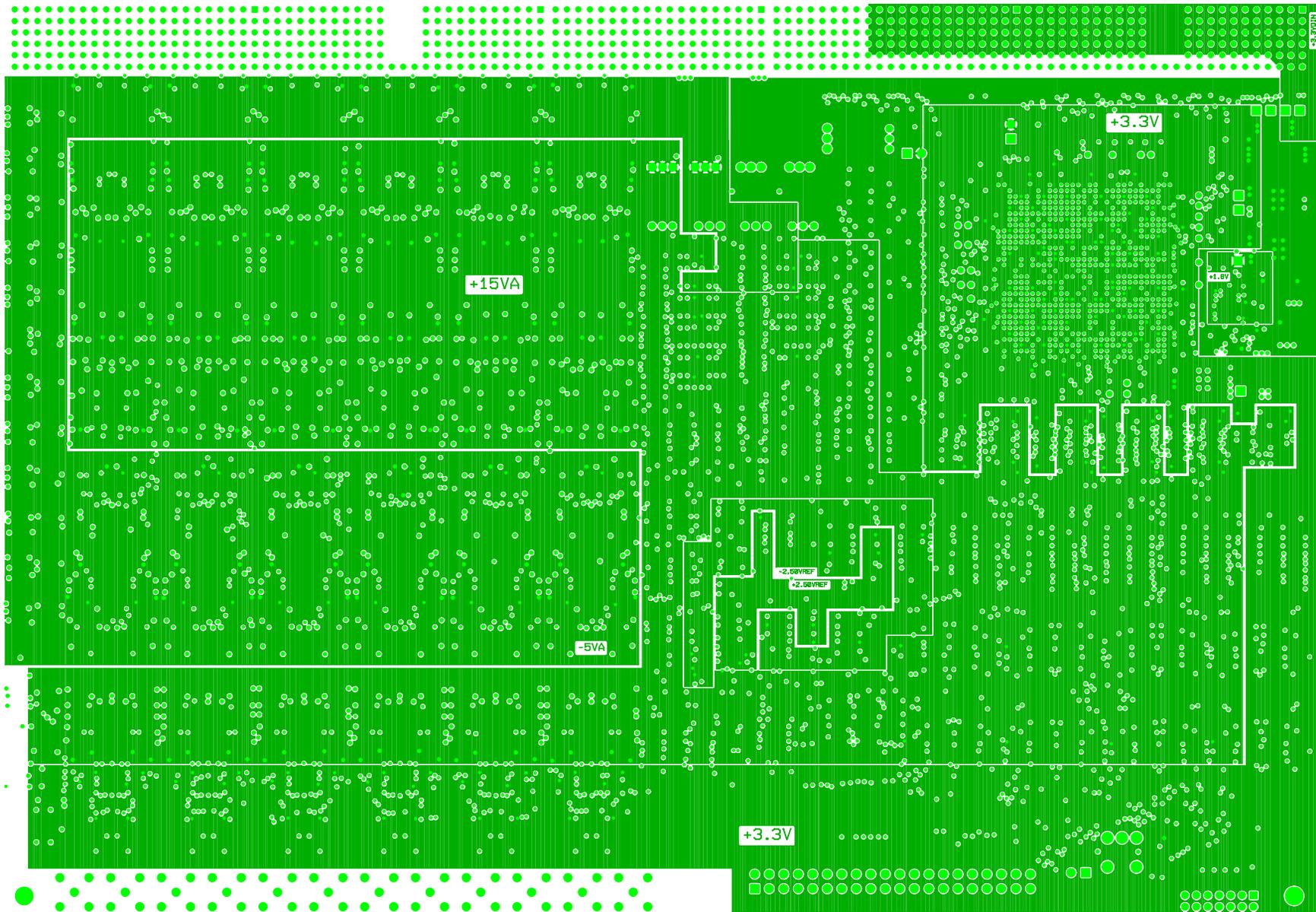
EtchLayer14.gds

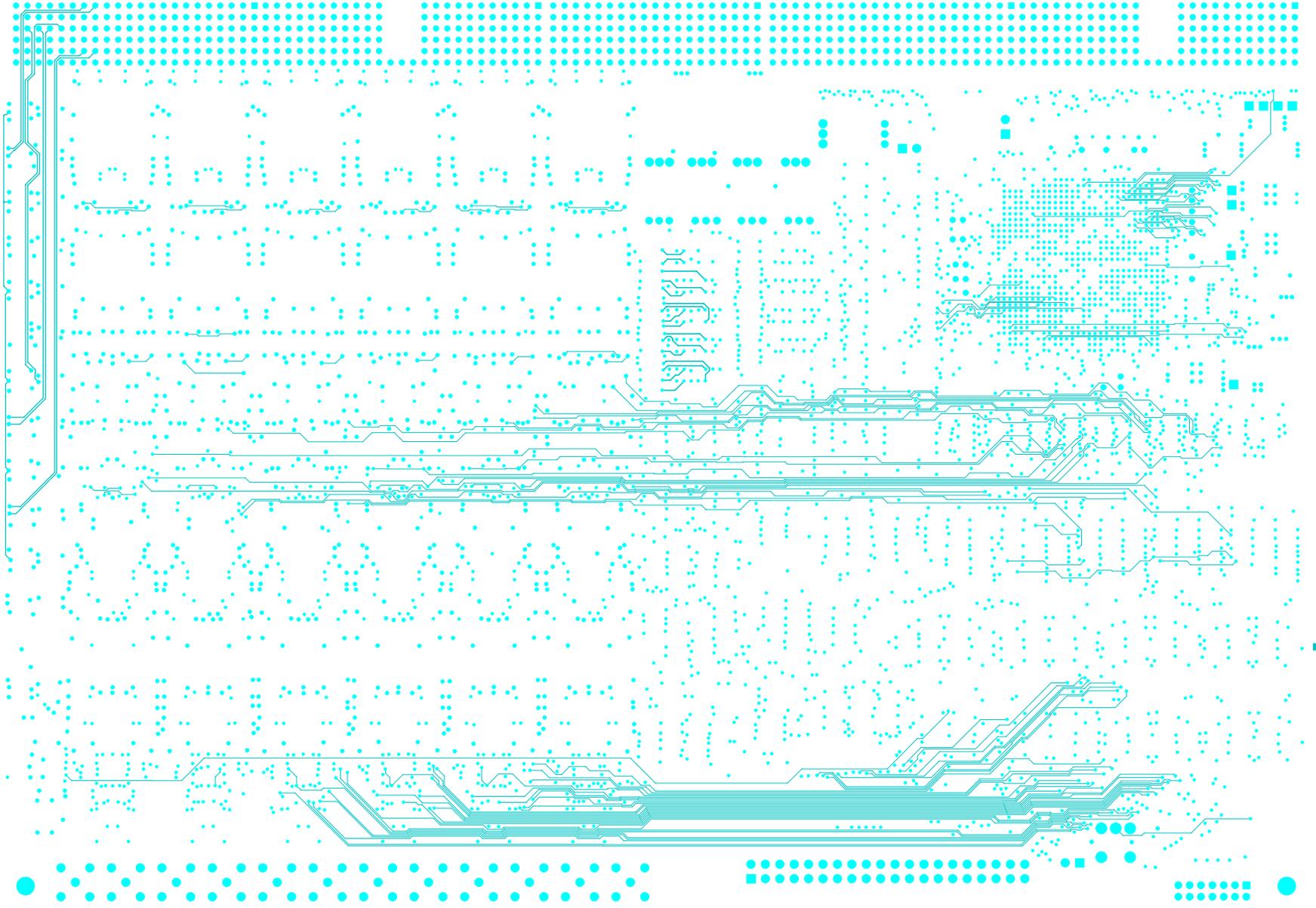




EtsbLayer13.gds

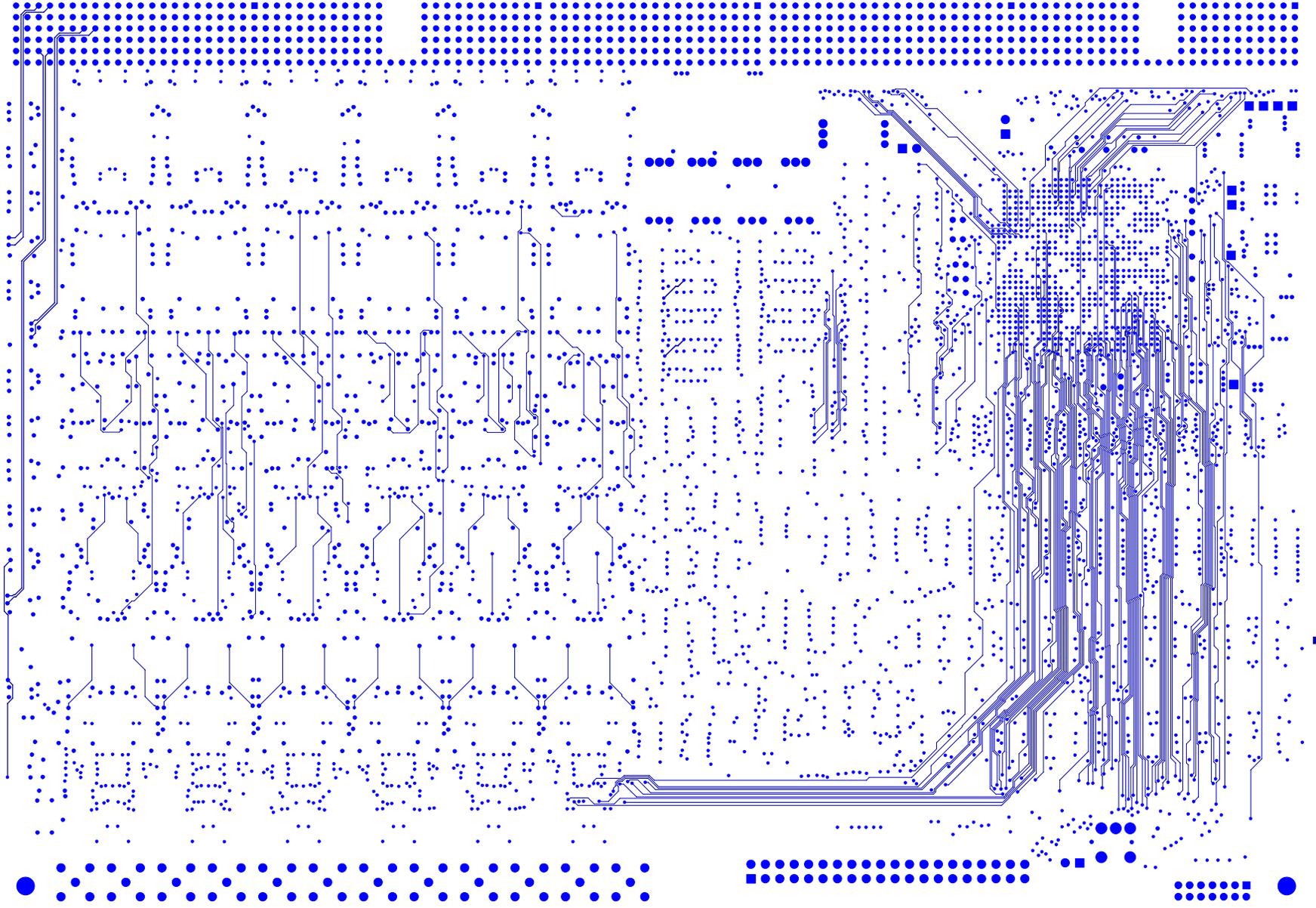
EtchLayer12.gds

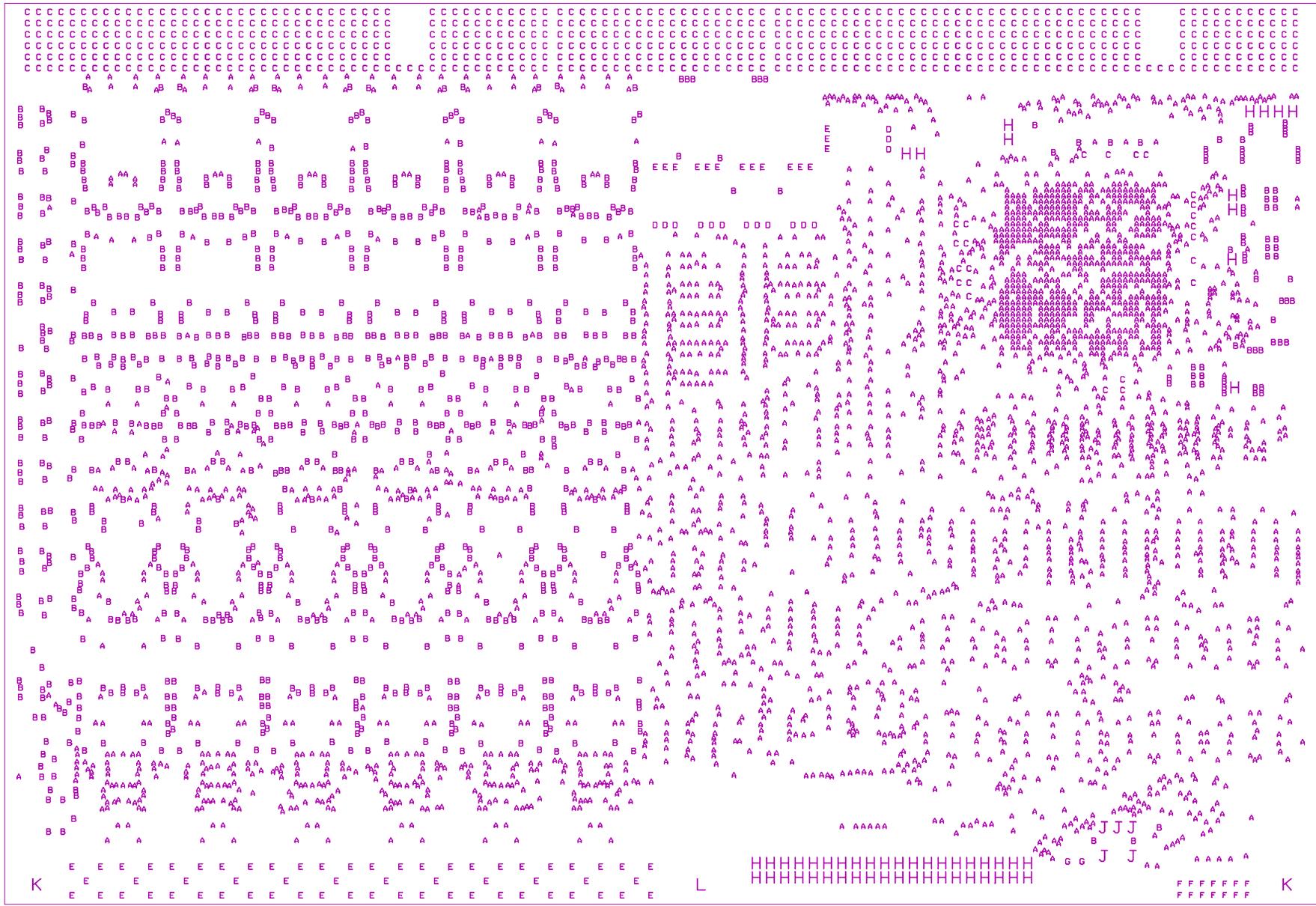




EtoHLayer11.gbr

EtoHLayer10.gbr





Through Holes						
Symbol	Diameter (in)	Tolerance (in)	Plated	Punched	Hole Name	Quantity
A	0.0100	+/- 0.0030	Yes	No	10th +/-3	3189
B	0.0150	+/- 0.0030	Yes	No	15th +/-3	1073
C	0.0240	+/- 0.0020	Yes	No	24th +/-2	671
D	0.0280	+/- 0.0030	Yes	No	28th +/-3	15
E	0.0340	+/- 0.0030	Yes	No	34th +/-3	75
F	0.0350	+/- 0.0030	Yes	No	35th +/-3	14
G	0.0360	+/- 0.0030	Yes	No	36th +/-3	2
H	0.0400	+/- 0.0030	Yes	No	40th +/-3	52
J	0.0470	+/- 0.0030	Yes	No	47th +/-3	5
K	0.1060	+/- 0.0040	Yes	No	106th +/-4	2
L	0.1200	+/- 0.0030	No	No	120th +/-3, non-plated	1

